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## Product Change Notification - RMES-05VMLN744

<b>Date:</b>	19 Feb 2018
<b>Product</b>	Piezoelectric Horn Drivers; Photoelectric Smoke Detector
<b>Category:</b>	
<b>Notification subject:</b>	CCB 2811 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected R&E Products available in 16L SOIC package at MMT assembly site.
<b>Notification text:</b>	<p><b>PCN Status:</b> Final notification</p> <p><b>PCN Type:</b> Manufacturing Change</p> <p><b>Microchip Parts Affected:</b> Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.</p> <p>NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).</p> <p><b>Description of Change:</b> Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected R&amp;E Products available in 16L SOIC package at MMT assembly site.</p> <p><b>Pre Change:</b> Gold (Au) bond wire</p> <p><b>Post Change:</b> Palladium coated copper with gold flash (CuPdAu) bond wire</p>

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	Microchip Technology Thailand (MMT)	Microchip Technology Thailand (MMT)
<b>Wire material</b>	Au	CuPdAu
<b>Die attach material</b>	2200D	2200D
<b>Molding compound material</b>	G600V	G600V
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**

None

**Reason for Change:**

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

March 19, 2018 (date code: 1812)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

**Time Table Summary:**

	<b>December 2016</b>					-->	<b>February 2018</b>				<b>March 2018</b>				
Workweek	48	49	50	51	52		05	06	07	08	09	10	11	12	13

Initial PCN Issue Date			X												
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date														X	

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report

**Revision History:**

**December 15, 2016:** Issued initial notification.

**February 19, 2018:** Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 19, 2018.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN\\_RMES-05VMLN744\\_Affected\\_CPN.pdf](#)
  - [PCN\\_RMES-05VMLN744\\_Qual Plan.pdf](#)
  - [PCN\\_RMES-05VMLN744\\_Affected\\_CPN.xlsx](#)

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PCN\_RMES-05VMLN744 CCB 2811 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected RE Products available in 16L SOIC package at MMT assembly site.

Affected Catalog Part Number

PCN_RMES-05VMLN744
CATALOG_PART_NBR
RE280S16TF
RE296S16F
RE296S16TF
RE297S16F
RE297S16TF
RE298S16F
RE298S16TF
RE299S16F
RE299S16TF
RE320S16F
RE320S16TF
RE321S16F
RE321S16TF
RE340S16F
RE340S16TF
RE342S16F
RE342S16TF
RE46C107S16F
RE46C107S16TF
RE46C109S16F
RE46C109S16TF
RE46C119S16F
RE46C119S16TF
RE46C140S16F
RE46C140S16TF
RE46C141S16F
RE46C141S16TF
RE46C143S16F
RE46C143S16TF
RE46C144S16F
RE46C144S16TF
RE46C145S16F
RE46C145S16F-AAA
RE46C145S16TF
RE46C145S16TF-AAA
RE46C165S16F
RE46C165S16TF
RE46C166S16F
RE46C166S16TF
RE46C167S16F
RE46C167S16TF
RE46C168S16F

PCN\_RMES-05VMLN744 CCB 2811 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected RE Products available in 16L SOIC package at MMT assembly site.

Affected Catalog Part Number

PCN_RMES-05VMLN744
CATALOG_PART_NBR
RE46C168S16TF
RE46C180S16F
RE46C180S16TF
RE46C190S16F
RE46C190S16TF
RE46C191S16F
RE46C191S16TF